

10-05-2009



To the Commissioner for Patents. Please

as thereof.

1. Name of Conveying Party(ies):

103576167

Name of Receiving Party(ies):

Wei-Yu CHEN
Jenn-Chang HWANG
Chih-Fang HUANG
Chien-Cheng CHEN

Name: National Tsing Hua University

Street Address: 101, Section 2, Kuang-Fu Road

3. Nature of Conveyance:

- Assignment
- Security Agreement
- Other:
- Merger
- Change of Name

City, State, Zip: Hsinchu, Taiwan 30013, R.O.C.

Execution Date: September 11, 2009

Additional name(s) and address(es) attached.

4. (A) Patent Application Number(s):

4. (B) Patent Number(s):

If this document is being filed together with a new application, the execution date of the application is:

September 11, 2009

Additional Numbers Attached.

Title: METHOD OF FABRICATING SILICON CARBIDE (SiC) LAYER

Attorney Docket No.: CHEN4396/EM

5. Name and Address of Party to whom Correspondence Concerning this Document Should be Mailed:

Name: Eugene Mar

Bacon & Thomas, PLLC
625 Slaters Lane Fourth Floor
Alexandria, VA 22314

23364
CUSTOMER NUMBER

Total Number of Applications and Patents Involved:

1

7. Total Fee:
(37 CFR 3.41)

\$40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit Account Number: 02-0200

9. Statement and Signature:

To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document.

Eugene Mar

September 25, 2009

Name of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments and document: 3

EM/bh

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ATTORNEY/DOCKET NO:

ASSIGNMENT BY INVENTOR(S) OF U.S. APPLICATION

WHEREAS, I am the original, first and sole inventor and I own (if only one name is listed below) or an original, first and joint inventor and the joint inventors own (if plural names are listed below) (referred to as "ASSIGNOR" below) the subject matter which is claimed and for which a patent is sought on the invention (referred to as the "INVENTION" below) entitled:

Title: **Method of Fabricating Silicon Carbide (SiC) Layer**

the specification of which (check one):

- is executed on even date herewith.
- was filed on (day-month-year) as U.S. Application Number
- was filed on (day-month-year) as PCT Application Number
- was executed on the following date(s) (day-month-year)

WHEREAS, **National Tsing Hua University**

having a postal address of **101, Section 2, Kuang-Fu Road, Hsinchu, Taiwan 30013, R.O.C.**

(referred to as "ASSIGNEE" below) desires to acquire the entire right, title and interest in and to the same in the U.S.;

NOW, THEREFORE, for good and valuable consideration, the receipt and adequacy of which is hereby acknowledged, ASSIGNOR, by these presents does sell, assign and transfer unto ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all patents granted on any division, continuation, continuation-in-part and reissue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent applications in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE's expense, to identify and communicate to ASSIGNEE at ASSIGNEE's request documents and information concerning the INVENTION that are within ASSIGNOR's possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR's obligations under this instrument shall extend to ASSIGNOR's heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all patents referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE's sole use and behoof; and for the use and behoof of ASSIGNEE's legal representatives and successors, to the full end of the term for which such patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

ASSIGNOR authorizes any member of the firm of Bacon & Thomas, PLLC to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

Full Name of First or Sole Inventor Wei-Yu CHEN	Post Office Address Department of Materials Science and Engineering, National Tsing Hua University, 101, Sec. II, Kuang-Fu Road,
Citizenship Taiwan R.O.C.	Residence (city, and either state or foreign country, MPEP §605.02) Hsin-Chu City 300, Taiwan R.O.C.
Date 9.11.2009	Signature Wei - Yu . Chen

See following page(s) for additional joint inventors.

ATTORNEY/DOCKET NO:

**SUPPLEMENTAL PAGE FOR AN
ASSIGNMENT BY INVENTOR(S) OF U.S. APPLICATION**

Full Name of Joint Inventor Jenn-Chang HWANG	Post Office Address Department of Materials Science and Engineering, National Tsing Hua University, 101, Sec. II, Kuang-Fu Road,
Citizenship Taiwan R.O.C.	Residence (city, and either state or foreign country, MPEP §605.02) Hsin-Chu City 300, Taiwan R.O.C.
Date <i>9, 11, 2009</i>	Signature <i>Jenn-Chang Hwang</i>

Full Name of Joint Inventor Chih-Fang HUANG	Post Office Address Department of Electrical Engineering, National Tsing Hua University, 101, Sec. II, Kuang-Fu Road,
Citizenship Taiwan R.O.C.	Residence (city, and either state or foreign country, MPEP §605.02) Hsin-Chu City 300, Taiwan R.O.C.
Date <i>9.11.2009</i>	Signature <i>Chih-Fang Huang</i>

Full Name of Joint Inventor Chien-Cheng CHEN	Post Office Address Department of Materials Science and Engineering, National Tsing Hua University, 101, Sec. II, Kuang-Fu Road,
Citizenship Taiwan R.O.C.	Residence (city, and either state or foreign country, MPEP §605.02) Hsin-Chu City 300, Taiwan R.O.C.
Date <i>9-11-2009</i>	Signature <i>Chien Cheng Chen</i>

Full Name of Joint Inventor	Post Office Address
Citizenship	Residence (city, and either state or foreign country, MPEP §605.02)
Date	Signature

See following page(s) for additional joint inventors.